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The need to cool Low- $T_c$  superconducting devices to liquid helium temperature (4.2 K) or below strongly limits its usability – liquid helium containers are not easy to transport and pose a safety risk in closed environments. The use of cryo-coolers can help, but their use is limited to more or less stationary applications in laboratory environments as long as the operation temperature is 4.2K or below. If one could operate the devices at higher temperature, the cooling requirements would become less stringent and the superconductive electronics systems could find much broader applications.

The diagram<sup>1</sup> demonstrates the big advantage of higher operating temperatures: it shows the cooler input power for 1 W of cooling as function of the operating temperature. The specific cooling power at 4.2 K is about 3 kW; the compressors for these cryo-coolers are quite bulky and can be noisy.

If one increases the operating temperature to 15 K, the specific cooling power is reduced to 600 W – already a significant increase in usability: rack mounting of the whole system is possible. If one further increases the operating temperature, e.g. to 77 K, the electrical input power drops to less than 30 W and makes desktop and even battery operated applications possible.

Starting in the 60's, when new superconducting materials with higher  $T_c$  were found, work started in order to adapt these materials to superconductive electronics applications. One of the first applications was a SQUID made from Nb<sub>3</sub>Sn by Wu and Falco<sup>2</sup> at Argonne National Laboratory in 1977.

<sup>1</sup> Slide made available by ter Brake, University of Twente, The Netherlands

<sup>&</sup>lt;sup>2</sup> C.T. Wu and C.M. Falco, Appl. Phys. Lett. 30, 609 (1977)



In the 1980's the effort to enhance the operation temperature of superconductive electronic devices increased: the group of Beasley at Stanford and my group in Giessen/Germany worked on the fabrication of Josephson junctions and SQUIDs from the A15 materials Nb<sub>3</sub>Sn (T<sub>c</sub> of 18.3 K) and Nb<sub>3</sub>Ge (T<sub>c</sub> of 23.2 K), respectively. Tunnel junctions from these materials are extremely difficult to fabricate – the high deposition temperatures for A15 materials starts chemical reactions at the interface with the barrier material and the diffusion is not negligible.

The Stanford group choose the route for Josephson junction fabrication via SNSjunctions<sup>1</sup>: they etched a step in the substrate and used shadow technique to deposit Nb<sub>3</sub>Sn on the planes, but not on the step. Then they deposited a Au- or Cu-layer across the step and thus created a Nb<sub>3</sub>Sn-Au-Nb<sub>3</sub>Sn SNS Josephson junction.

In Giessen we choose a different route to reach the highest operating temperature possible at that time:  $Nb_3Ge$  has a  $T_c$  of 23.2 K, and as thin film a  $T_c$  of about 21 K can be reached. Using coherent vortex motion in nano-bridges allows Josephson junctions that can be operated nearly to the  $T_c$  of the superconducting films. I converted an old SEM with beam blanker to an electron beam writer, that allowed us to make structures down to 40 nm; better than the 100 nm we needed for coherent vortex motion in a hyperbolic  $Nb_3Ge$  nano-bridge.

Together with Bernd David<sup>2</sup>, we made first Nb<sub>3</sub>Ge nano-bridge SQUIDs that we operated in liquid hydrogen at 20.2 K.

<sup>1</sup> A. De Lozanne, M. Dilorio and M.R. Beasley, Physica B+C, 108, 1027 (1981)

<sup>&</sup>lt;sup>2</sup> H. Rogalla and B. David, J. Appl. Phys. 55, 3441 (1984)



The Nb<sub>3</sub>Ge nano-bridge technique turned out to be very powerful and we were able to create many junctions in series with a  $T_c$  close to 20 K.

An important step towards an integrated superconductive electronics is the availability of a multilayer technique. We found that a sputtered amorphous interlayer resisted recrystallization and chemical reaction with Nb<sub>3</sub>Ge long enough to deposit a  $2^{nd}$  layer of Nb<sub>3</sub>Ge onto it and that etching openings in the interlayer resulted in vias between the layers with high critical current density. Applying the Nb<sub>3</sub>Ge multilayer technique, we fabricated a first fully integrated Nb<sub>3</sub>Ge SQUID of the Ketchen-type which operated at temperatures up to 20 K.

<sup>1</sup> H. Rogalla, B. David and M. Mück, in "SQUID '85 Superconducting Quantum Interference Devices and their Applications", ed. H.-D. Hahlbohm and H. Lübbig, Walter de Gruyter, 671 (1985)



The in 1986 the superconductive world changed dramatically, when Bednorz and Müller<sup>1</sup> published their article showing superconductivity in LaBaCuO near 30 K. And it changed even more dramatically when Chu et al.<sup>2</sup> showed superconductivity at 92 K in YBaCuO. Till then,  $T_c$  increased with time in a typical effort driven manner, linear in a semi-logarithmic plot of  $T_c$  as function of time. Within a few years  $T_c$  rose to 138 K (HgBaCaCuO) without pressure and up to 203 K (H<sub>2</sub>S) with extreme pressure.

<sup>1</sup> J.G. Bednorz and K.A. Müller, Zeitschrift für Physik B**64**, 189–193 (1986)
 <sup>2</sup> M.K. Wu, J.R. Ashburn, C.J. Torng, P.H. Hor, R.L. Meng, L. Gao, Z.J. Huang, Y.Q. Wang, C.W. Chu, Phys. Rev. Lett. 58, 908 (1987)



Just to make YBaCuO was simple – no need for ultra-high vacuum and complicated deposition techniques: just some chemicals could be wet-processed in a 'cake-recipe manner' and baked at high temperatures. This technical advantage had a bad science-policy consequence: since practically all laboratories could make it, a run on projects started and competence was not an important criterion anymore, but proposals with shiny promises in a time frame of months had a better chance than realistic ones with a time frame of many years. The downfall of High-Tc superconductive electronics was pre-programmed: many projects failed badly and funding became sparse. Only very few groups survived with funding that made long-term goals nearly impossible.



Once one had made a piece of YBCO one could show superconductivity with a levitating magnet - an excellent demonstration of superconductivity still widely used today. Jim Zimmerman in his very practical approach to science had the idea to make an rf-SQUID from such a piece of bulk polycrystalline YBCO: breaking the polycrystalline material and press it together in a controlled fashion created an adjustable 'break junction' showing Josephson behavior. Such a SQUID was shown to work even at 81K and could be used for the first rf-SQUID experiments in liquid nitrogen.

In 1987 thin films were deposited onto different single-crystal substrates in a 2-step process resulting in polycrystalline thin films. The grain boundaries worked as Josephson junctions and Roger Koch of IBM Yorktown Height and my group in Twente/Netherlands demonstrated dc-SQUID behavior in SQUID structures etched into such polycrystalline films.



Grain boundaries were and are still widely used as High-T<sub>c</sub> Josephson junctions. Different techniques were developed over time to produce reproducible Josephson junctions this way: people at Conductus Inc. developed 'template junctions' using the change in orientation with which YBaCuO-films grew on single crystal CeO-films and other single crystal films like MgO. They also developed an advanced single crystal multilayer technology for the fabrication of superconductive electronics. 'Mr. SQUID', a simple dc-SQUID system for demonstration and educational purposes, has been developed in that time and is still available today.

An alternative technique leads to the the step-edge junctions. An YBaCuO-layer deposited onto a step, etched into a substrate (often MgO) with a sharp edge at the top and rounded at the bottom, results into two grain boundaries: a small one with a low critical-current density at the top and one with a high critical-current density at the bottom. Such junctions have excellent characteristics and a high  $T_c$ . Since the growth of the grain boundaries is still a quite random process, there is still quite some spread in the critical currents density of such junctions. The sketch of a step-edge junction by Shane Cybart demonstrates the randomness along the upper junction edge. Nevertheless, they are excellent for applications where such a spread is less important and where a high  $I_cR_n$ -product and a high  $T_c$  is needed.



The currently most widely used grain-boundary Josephson junctions are the bicrystal junctions, invented by Chaudhari, Mannhart et al. at IBM in 1988. The grainboundary forms at the interface of two single crystal substrates, welded together under a well defined angle. Extensive investigation by Hilgenkamp and Mannhart showed that the critical current density through such junctions decreases linearly in a semi-logarithmic plot with the angle between the main axes of the bi-crystal. Thus the critical current density can already be determined to some degree by choosing the angle of the bi-crystal. A disadvantage for more complex applications is the linear geometry of the grain boundary.

In 1994, Hans Hilgenkamp prepared already a fully functional integrated dc SQUID in my group in Twente, using a bi-crystal substrate.



From early on some groups tried to create High-T<sub>c</sub> Josephson junctions by controlled damaging a YBaCuO thin film with electron or ion beams. Especially the ion-beam work of Shane Cybart and Bob Dynes showed some promising results: they used e-beam lithography to create a very narrow slit in an electron beam resist and then used the slit as mask for a subsequent ion-bombardment step. The resulting junctions showed quite good IV-characteristics for higher dosages, but then also suppressed T<sub>c</sub>.



The irradiation of the thin films was simulated by Shane Cybart. These simulations show the widening of the damaged area at the bottom of the film. At low dosages and/or low temperatures, the IV-characteristics don't look RSJ-like, but are flux-flow dominated.



It was quite clear from the beginning, that the growth and the properties of grain boundaries could not be well controlled. Attempts to fabricate planar junctions had failed because of the layered structure of the high-Tc superconductors. It was clear that one had to use a quasi-planar epitaxial technique and that one had to get access to the CuO-planes for junctions with high  $I_c R_p$ -product and some reproducibility. During a coffee break with my group in Twente, I had the idea to make a step-edge junction without step, but replace it by a flat ramp, so that layers could grow epitaxially on the ramp – and the ramp would give access to the CuO-planes. The idea was tried in my group and resulted in the first fully epitaxial High-Tc Josephson junction, which we called 'ramp-type junction'. This junction type allowed to use different barrier materials for strong SNS-type coupling to nearly SIS-coupling. Especially interesting was the use of PrBaCuO as barrier material because it allowed to adjust the critical current density independent of the resistance of the barrier: the former was adjusted by the thickness of the barrier, the latter by the amount of doping of the PrBaCuO by Ga. This allowed to adjust the I<sub>c</sub>R<sub>n</sub> product over a wide range.

These junctions were very successful and used in many laboratories, in the original configuration or in a slightly different configuration as 'interface engineered junctions'. Till now they are the only successful planar junctions. Their preparation is non-trivial and the reproducibility limited to circuits with up to 100 junctions.



In Japan the ramp-type junctions were very successfully used in conjunction with their  $SrSnO_2$ -based multilayer technique. Three superconducting layers were realized. In Twente we also developed a multilayer technique with up to three superconducting layers above a ground-plane. Even though it worked very well, the limited support made it very difficult to keep the complicated multilayer technique available in Twente. It was discontinued in the early 2000s. Till a short while ago it was still available at ISTEC in Japan.



The Japanese High-T<sub>c</sub> electronics program was especially successful at ISTEC. The multilayer technique together with ramp-type junctions allowed for circuits with up to 100 Josephson junctions. Among other circuits the demonstrated the operation of a DC-to-SFQ converter connected to a 96 junction JTL and an SFQ-to-DC converter. In the Japanese industry a ring-oscillator (Toshiba) and also a  $\Sigma\Delta$ -modulator (Hitachi) was demonstrated with a clock frequency of 100 GHZ. In Twente a similar modulator was operated at above 150 GHz.

	HTS Electronics	Applications	
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There is only room for very few applications to be shown here. One of the early and very successful demonstrators is the 100 GHz sampling scope of Hidaka, at that time with NEC in Japan. It is one of the first demonstrations of a complete system around an High-T<sub>c</sub> electronics circuit, mounted on a cryo-cooler and showing a performance that was not met by semiconductor circuits at that time. They showed operation, e.g., by sampling a 20 GHz signal with the 100 GHz sampler.



This Hitachi system uses a 4x4 array of HTS SQUIDs with planar gradiometers. A 36-sensor version and an LTS version is also available that uses 64 sensors. However, these Hitachi systems are all required to be housed in an enclosure made of  $\mu$  metal. As a result, these Hitachi system are very expensive. The Hitachi system allows the time resolved recording of the current distribution in the heart.



During the development of the Airbus A380, it was important to test the wing structure for cracks, especially around bolts trough compound plates. In a cooperation between Rohmann, Airbus, Lufthansa, ILK Dresden, University of Giessen and later also the Research Center Jülich, an High-T<sub>c</sub> test system was developed and used in the wing testing.



The conventional eddy-current system by Rohmann-company was not able to detect certain cracks, whereas the HTS rf-SQUID system was able to clearly detect the cracks.



Because of their low losses, High-T<sub>c</sub> superconducting filters were especially adapted to applications where steep filter characteristics were needed. In the commercial field, channel separation and an extended range because of reduced losses were an important argument to apply superconducting filters in base stations for cellular telephony. Superconducting Technologies among other companies fabricated such filters, that were very compact and could be realized in a one-layer technique.



These filters showed excellent channel separation, much better than typical conventional filters.



Because of the low electrical input power needed to cool these filters, they could be housed in a small cryostat directly connected to a cryo-cooler. Together with some small control electronics it could be housed in a 14" sub-unit for rack mounting.

Status in 2016 on HTS Josephson Junctions				
For practical applications:				
There are <b>NO</b> practical planar HTS Josephson junctions !				
(The only working ones were the ramp-type junctions).				
The best we have after about 30 years of High-T <sub>c</sub> :				
<ul> <li>Bi-crystal and step-edge grain boundary junctions</li> </ul>				
<ul> <li>Ion-damaged junctions</li> </ul>				
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Realistically one can say that over the last 50 years not many High- $T_c$  superconductive electronics applications have survived and create a notable amount of income for the medical or electronics industry. There are interesting niche applications, but overall the standing of this technology is somewhat disappointing. The prime reason is the lag in having a Josephson junction technology available which can create 10,000s of Josephson junction with high  $T_c$ , high  $I_cR_n$ -product and high reproducibility with narrow critical-current density margins. The best we currently have are bi-crystal and grain boundary junctions and to a lesser extend ion-damage junctions.

But there is some light at the horizon: there is recent progress in ion-damage junctions and also in step-edge junction.



Recently, Shane Cybart and his group showed that direct writing of ion-damage junctions with a Zeiss 0.5 nm He-ion source results in junctions that show good RSJ-like IV-characteristics at high dosages, which constant resistance as function of temperature and very localized damage. Also the stability of these junctions seems to be good. Still, the  $I_cR_n$ -product is low and the  $T_c$  could be improved. Nevertheless, by changing preparation parameters like beam energy and film thickness, one could expect further improvements in the junction characteristics. This technique has the advantage that the junctions can be written anywhere and would also be compatible to a multilayer process, since they could be written in the top-layer of a layer stack.



The group of Cathy Foley of CSIRO has recently demonstrated an impressive result by fabricating SQIFFs with more than 100,000 step-edge junctions. Even though step-edge junctions are very likely bound to a 1-layer technique, the good reproducibility of these junctions opens new areas for High-T<sub>c</sub> SQUID arrays and SQIFFs with excellent characteristics. Still, the spread in critical-current density and the likely limit to one superconducting layer makes this junction type not (yet) applicable to digital superconductive electronics applications.

<sup>1</sup> Data on this slide made available by Cathy Foley, CSIRO.

In view of these new results in High-T<sub>c</sub> Josephson junction technology, it is time to revisit some of the applications which had been giving up in the past because of a lack of a well-developed Josephson junction technology. Together with the advantages in cryo-cooler techniques, some applications might have a good chance to make it into the commercial/military market.